

DECLARATION FOR PATENT APPLICATION (WITH POWER OF ATTORNEY)

As an inventor named below or on any attached continuation page, I hereby declare that:
My residence, post office address and citizenship are as stated next to my name.

I believe that I am the original, first and sole inventor (if only one name is listed below) or an original, first and joint inventor (if plural names are listed below) of the subject matter which is claimed and for which a patent is sought on the invention entitled CASTELLATED CHIP-SCALE PACKAGES AND METHODS FOR FABRICATING THE SAME, the specification of which (check one):

- ☒ is attached hereto.
- ☐ was filed on _____ as United States application serial no. _____ and was amended on _____.
- ☐ was filed on _____ as PCT international application no. _____ and was amended under PCT Article 19 on _____.

I hereby state that I have reviewed and understand the contents of the above-identified specification, including the claims, as amended by any amendment referred to above.

I acknowledge the duty to disclose to the U.S. Patent and Trademark Office all information known to me to be material to the patentability of the subject matter claimed in this application, as "materiality" is defined in Title 37, Code of Federal Regulations § 1.56.

I hereby claim foreign priority benefits under Title 35, United States Code, § 119(a)-(d) or § 365(b) of any foreign application(s) for patent or inventor's certificate or § 365(a) of any PCT international application(s) designating at least one country other than the United States of America listed below and on any attached continuation page and have also identified below and on any attached continuation page any foreign application for patent or inventor's certificate or any PCT international application(s) designating at least one country other than the United States of America having a filing date before that of the application(s) on which priority is claimed.

Prior foreign/PCT application(s):

<u>200305779-1.</u>	<u>Singapore</u>	<u>30/09/2003</u>	Priority <u>X</u>	Claimed
(number)	(country)	(day/month/year filed)	Yes	No
_____	_____	_____	_____	_____
(number)	(country)	(day/month/year filed)	Yes	No

I hereby claim the benefit under Title 35, United States Code, § 120 of any United States application(s) or § 365(c) of PCT international application(s) designating the United States of America listed below and on any attached continuation page and, insofar as the subject matter of each of the claims of this application is not disclosed in any such prior application in the manner provided by the first paragraph of Title 35, United States Code, § 112, I acknowledge the duty to disclose to the U.S. Patent and Trademark Office all information known to me to be material to patentability as defined in Title 37, Code of Federal Regulations § 1.56 which became available

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Invention Title: CASTELLATED CHIP-SCALE PACKAGES AND METHODS FOR FABRICATING THE SAME
between the filing date of such prior application and the national or PCT international filing date of this application:

_____	_____	_____
(application serial no.)	(filing date)	(status—pending, patented or abandoned)
_____	_____	_____
(application serial no.)	(filing date)	(status—pending, patented or abandoned)

I hereby claim the benefit under Title 35, United States Code, § 119(e) of any United States provisional application(s) listed below:

_____	_____
(provisional application no.)	(filing date)

I hereby appoint the following Registered Practitioners to prosecute this application and to transact all business in the Patent and Trademark Office connected therewith:

David V. Trask, Reg. No. 22,012	William S. Britt, Reg. No. 20,969
Laurence B. Bond, Reg. No. 30,549	Joseph A. Walkowski, Reg. No. 28,765
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Address all correspondence to: Brick G. Power, telephone no. (801) 532-1922.

TRASKBRITT, PC
P.O. Box 2550
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I hereby declare that all statements made herein of my own knowledge are true and that all statements made on information and belief are believed to be true; and further that these statements were made with the knowledge that willful false statements and the like so made are punishable by

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Invention Title: CASTELLATED CHIP-SCALE PACKAGES AND METHODS FOR FABRICATING THE SAME

fine or imprisonment, or both, under Section 1001 of Title 18 of the United States Code and that such willful false statements may jeopardize the validity of the application or any patent issued thereon.

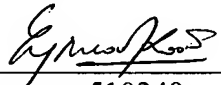
Full name of first joint inventor: Suan Jeung Boon

Inventor's signature  Date 12 Nov 2003
Residence: Singapore, 799499
Citizenship: Republic of Singapore
Post Office Address: 271-A Jin Kayu, Singapore 799499

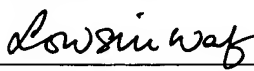
Full name of second joint inventor: Yong Poo Chia

Inventor's signature  Date 12 Nov 03
Residence: Singapore, 679976
Citizenship: Republic of Singapore
Post Office Address: Blk 37 #10-03 Bangkit Road, Singapore 679976

Full name of third joint inventor: Meow Koon Eng

Inventor's signature  Date 17 Nov 03
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Citizenship: Republic of Singapore
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Full name of fourth joint inventor: Siu Waf Low

Inventor's signature  Date 12 Nov 2003
Residence: Singapore, 239282
Citizenship: Malaysia
Post Office Address: 30, Lengkok Angsa, Singapore 239282

CONFIDENTIAL

WRITTEN AUTHORITY SOUGHT UNDER SECTION 34 OF THE PATENTS ACT (CAP. 221)

PART I (To be completed by the person seeking the request)

*Name & Address of Person (s) (Inventor / Applicant / Others **)	BOON, Suan Jeung 271-A, Jalan Kayu Singapore 799499	
*Name & Address of Person (s) (Inventor / Applicant / Others **)	CHIA, Yong Poo Block 37, Bangkit Road, #10-03 Singapore 679976	
*Name & Address of Person (s) (Inventor / Applicant / Others **)	ENG, Meow Koon Block 249, Pasir Ris Street 21, #02-125 Singapore 510249	
*Name & Address of Person (s) (Inventor / Applicant / Others **)	LOW, Siu Waf 30, Lengkok Angsa Singapore 239282	
Title of Invention	Castellated Chip-Scale Packages and Methods for Fabricating the Same	
Country in which Protection is Sought	U.S.A.	
Address for Service in Singapore	Arthur Loke Bernard Rada & Lee 9 Temasek Boulevard #23-01 Suntec Tower Two Singapore 038989	
Preferred Mode of Response from the Registrar (Please tick one of the following boxes and complete the corresponding blanks): <input checked="" type="checkbox"/> By Fax (Fax number is 6339 4991) <input type="checkbox"/> By Hand (To be collected by) <input type="checkbox"/> By normal, ordinary local mail.		
Contact No.	Telephone: 6434 2223 (Patsy Koh)	Pager:
Brief & Concise Description of the Invention (Use separate sheet)	: Please see attached.	
Date of submission to the Registry of Patents (SG)	: 25 September 2003	

PART II (To be completed by the Registry of Patents)

With regard to the above matter received by the Registry, written authority is / is not ** granted under Section 34 of the Patents Act (Cap. 221) to the above-mentioned applicant(s) and inventor(s) to file or cause to be filed the patent application outside Singapore for the invention mentioned in Part I.

25/09/2003
Date

* Attached additional sheet if necessary
** Delete as appropriate

Name & Signature

Our Registrar

